IPC ASSOCIATION CO ELECTRONICS IN	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights resolutions international and Pan-American copyright conventions.			All rights reserved unentions.	nder both	This document is a declaration of the substances within the manufacturer level parts, the declaration encompasses all lower level materials for which				rer listed it which the m	tem. Note: i	f the item is an as has engineering	sembly with low responsibility.		
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	ials and Mfg Information			
upplier Ir	nformation														
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*				
onsemi											2024-05-03				
Contact Name	e	Title - Contact			1	Phone - Contact*				Email - Contact*					
Product-Env	y-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized R	Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Dat	te Versi	ion	Manufacturing Site	,	Weight*	UOM	Unit Type	
		VEC2315-TL-H PCH+PCH 4V DRI		RIVE SERIES		2024-05-03	-05-03 CNG		CNG	:	16.51	mg	Each		
Ianufactu	uring Proccess Informa	ation													
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Tempera		ture Max Time at Peak Tempera		ure Numb	er of Reflow Cyc	eles			
contains Bi		CU Alloy 1			260 C		30	secon	ds 3						
omments															
vel 1 - maxii	mum time at peak temperat	ture during so	ldering is 10-	30 seconds											
or more info	ormation regarding materia	l composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.77	mg	Supplier	Silicon (Si)	7440-21-3		0.77	mg
Die Attach Solder	0.48	mg	Supplier	Silver (Ag)	7440-22-4		0.012	mg
			A	Lead (Pb)	7439-92-1	7a	0.444	mg
			Supplier	Tin (Sn)	7440-31-5		0.024	mg
Lead Frame	7.45	mg	Supplier	Silver (Ag)	7440-22-4		0.1646	mg
			Supplier	Tin (Sn)	7440-31-5		0.0179	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0156	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0179	mg
			В	Nickel (Ni)	7440-02-0		0.0283	mg
			Supplier	Copper (Cu)	7440-50-8		7.2056	mg
Mold Compound-Black	7.4	mg		Epoxy Phenol Resin	proprietary data		0.0592	mg
			Supplier	Carbon Black (C)	1333-86-4		0.074	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.444	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.92	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.888	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0148	mg
Plating	0.14	mg	В	Bismuth (Bi)	7440-69-9		0.0008	mg
			Supplier	Tin (Sn)	7440-31-5		0.1392	mg
Wire Bond - Au	0.27	mg	Supplier	Gold (Au)	7440-57-5		0.27	mg